
PCB Layout and Design Guide for CH7101B

HDMI to VGA Converter

1.0 INTRODUCTION

The CH7101B is a low-cost, low-power semiconductor device, which can convert HDMI signals into VGA outputs with IIS or SPDIF audio output.

This application note focuses only on the basic PCB layout and design guidelines for CH7101B HDMI to VGA Converter. Guidelines in component placement, power supply decoupling, grounding, input /output signal interface are discussed in this document.

The discussion and figures that follow reflect and describe connections based on the 40-pin QFN package of the CH7101B. Please refer to the CH7101B datasheet for the details of the pin assignments.

2.0 COMPONENT PLACEMENT AND DESIGN CONSIDERATIONS

Components associated with the CH7101B should be placed as close as possible to the respective pins. The following discussion will describe guidelines on how to connect critical pins, as well as describe the guidelines for the placement and layout of components associated with these pins.

2.1 Power Supply Decoupling

The optimum power supply decoupling is accomplished by placing a 0.1 μ F ceramic capacitor to each of the power supply pins as shown in **Figure 1**. These capacitors (C1, C2, C4, C6, C7, C9, C10, C12) should be connected as close as possible to their respective power and ground pins using short and wide traces to minimize lead inductance. Whenever possible, a physical connecting trace should connect the ground pins of the decoupling capacitors to the CH7101B ground pins, in addition to ground vias.

2.1.1 Ground Pins

The grounds of the CH7101B should be connected to a common ground plane to provide a low impedance return path for the supply currents. Whenever possible, each of the CH7101B ground pins should be connected to its respective decoupling capacitor ground lead directly, then connected to the ground plane through a ground via. Short and wide traces should be used to minimize the lead inductance. Refer to **Table 1** for the Ground pins assignment.

2.1.2 Power Supply Pins

The power supply includes VDDPLL, DVDD, AVCC, AVCC_DAC, and AVDD. Refer to **Table 1** for the Power supply pins assignment. Refer to **Figure 1** for Power Supply Decoupling.

Table 1: Power Supply Pins Assignment of the CH7101B (QFN)

Pin Assignment	# Of Pins	Type	Symbol	Description
1	1	Power	VDDPLL	PLL Power Supply (1.2V)
2, 18	2	Power	DVDD	Digital supply voltage (1.2V)
3, 19	2	GND	DGND	Digital Ground
11, 38	2	Power	AVCC	Analog supply voltage (3.3V)
24, 27	2	Power	AVCC_DAC	DAC power supply (2.5V~3.3V)
35	1	Power	AVDD	HDMI receiver power supply (1.2V)
Thermal pad	1	Ground	GND	Power supply ground

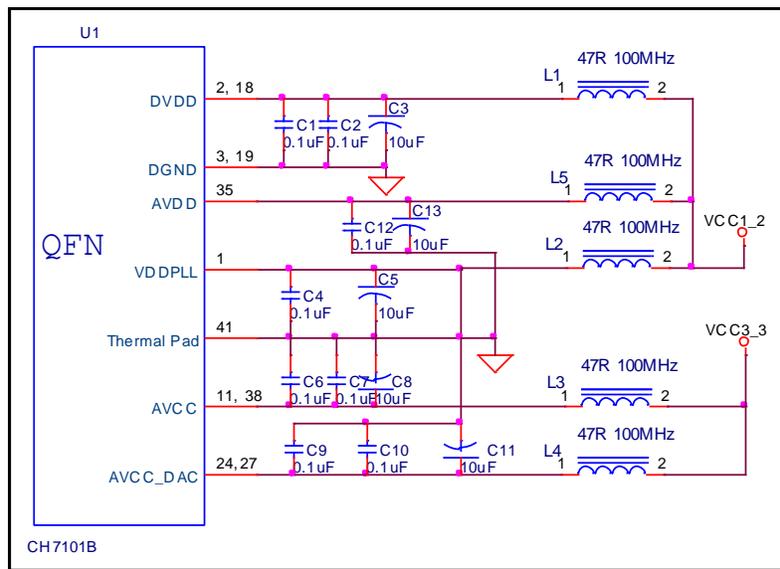


Figure 1: Power Supply Decoupling and Distribution

Note: All the Ferrite Beads described in this document are recommended to have an impedance of less than 0.05Ω at DC; 23Ω at 25MHz & 47Ω at 100MHz. Please refer to Fair Rite part #2743019447 for details or an equivalent part can be used for the diagram.

2.2 Internal Reference Pins

• RBIAS pin

This pin sets the DAC current. A $10 \text{ K}\Omega$, 1% tolerance resistor should be connected between RBIAS and GND as shown in **Figure 2**. A smaller resistance will create more DAC current. This resistor should be placed with short and wide traces as near as possible to CH7101B.

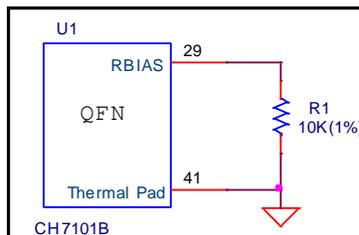


Figure 2: RBIAS pin connection

2.3 General Control Pins

• RB

This pin is the chip reset pin for CH7101B, which is internally pulled-up, places the device in the power on reset condition when this pin is low. A power-reset switch can be placed on the RB pin on the PCB as a hardware reset for CH7101B as shown in **Figure 3**. When the pin is high, the reset function can also be controlled through the serial port.

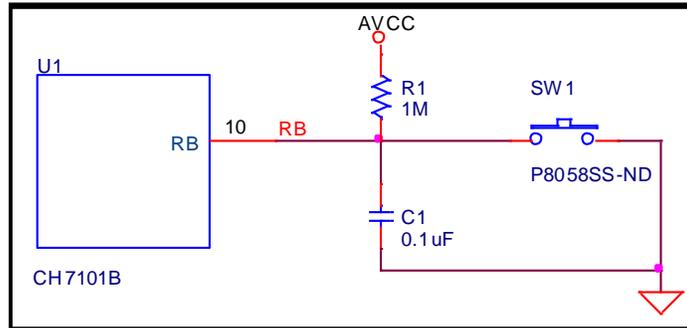


Figure 3: RB pin connection

• On chip power-on reset function’s sequence

There are two methods for chip power-on reset.

1. The RB signal can be generated by on board Resistor and Capacitor delay, which can be refer to **Figure 3**. For hardware circuit, please refer to **2.3 RB**.

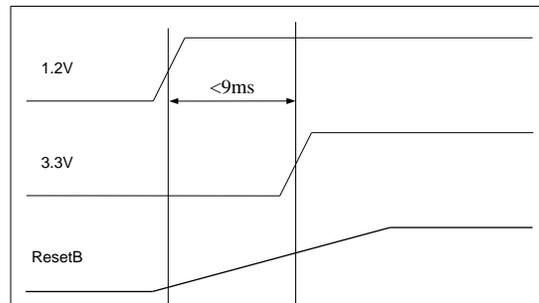


Figure 4: Power-on Reset Function’s Sequence on board

2. RB signal is generate by system global reset. In this case, 1.2V should be earlier than 3.3V, the power supply should be valid and stable for at least 20ms before the reset signal is valid. The pulse width of valid reset signal should be at least 100us. Otherwise, the chip can’t work well. The timing is shown in **Figure 5**.

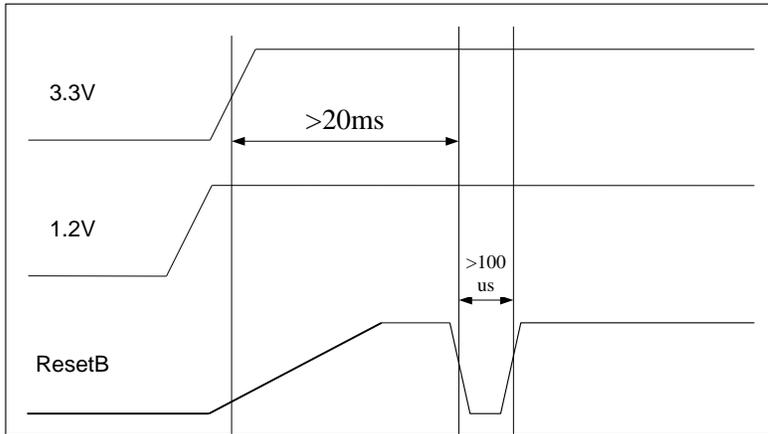


Figure 5: Power-on Reset Function's Sequence external global reset

Note:

1. The rising threshold of RB is 2.4V.
2. The falling threshold of RB is 0.4V.

• **GPIO [1:0]**

These pins are general-purpose input/output. Refer to reference schematic.

2.4 Serial Port Control for CH7101B

• **SPC0 and SPD0**

SPD0 and SPC0 function as a serial interface where SPD0 is bi-directional data and SPC0 is an input only serial clock. In the reference design, SPD0 and SPC0 pins are pulled up to +3.3V with 6.8K resistors always as shown in **Figure 6**.

• **DDC_SCL and DDC_SDA**

DDC_SCL and DDC_SDA are used to interface with the DDC of HDMI Source or transmitter and the serial PROM. This DDC pair needs to be pulled up to 5V through 47 KΩ resistors (Refer to **Figure 6**).

• **VGA_SCL and VGA_SDA**

VGA_SCL and VGA_SDA are used to interface with the DDC of VGA receiver and the serial PROM. This DDC pair needs to be pulled up to 5V through 1.8 KΩ resistors (Refer to **Figure 6**).

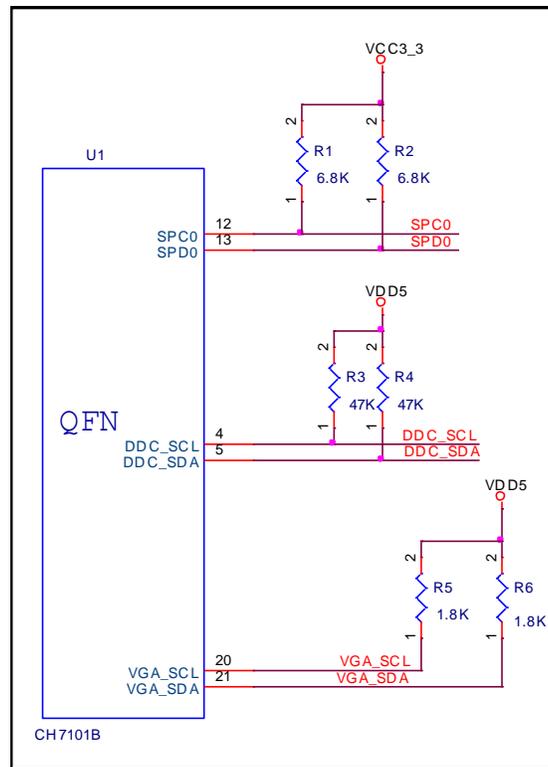


Figure 6: Serial Port Control

2.5 HDMI receiver Pins

The RCP, RCN, RD [2:0] P, RD [2:0] N signals are high frequency differential signals that need to be routed with special precautions. Since those signals are differential, they must be routed in pairs.

2.5.1 Differential Pair Impedance

To match the external cable impedance and maintain the maximal energy efficiency it is important to meet the impedance target of $100\text{-}\Omega \pm 10\%$ for the differential data/clock traces. The restriction of this impedance target is to prevent any loss of signal strengths resulting from a reflection of unwanted signals. The impedance can be acquired by proper design of trace length, trace width, signal layer thickness, board dielectric, etc. The HDMI differential pairs should be routed on the top layer directly to the HDMI connector pads if possible.

2.5.2 Trace Routing Length

To prevent from capacitive and impedance loading, trace lengths should be kept as minimal as possible. Vias and bends should always be minimized; inductive effects may be introduced, causing spikes in the signals. Trace routing lengths from CH7101B to the HDMI connector are limited to a maximum of 2 inches. The CH7101B should be as close to the HDMI connector as possible.

2.5.3 Length Matching for Differential Pairs

The HDMI specifies the intra-pair skew and the inter-pair skew as in **Table 2**. The intra-pair skew is the maximum allowable time difference on both low-to-high and high-to-low transitions between the true and complement signals. The inter-pair skew is the maximum allowable time difference on both low-to-high and high-to-low transitions between any two single-ended data signals that do not constitute a differential pair.

Table 2: Maximum Skews for the HDMI Transmitter

Skew Type	Maximum at Transmitter
Intra-Pair Skew	0.15 T _{bit}
Inter-Pair Skew	0.20 T _{Pixel}

Where T_{bit} is defined as the reciprocal of Data Transfer Rate and T_{Pixel} is defined as the reciprocal of Clock Rate. Therefore, T_{Pixel} is 10 times T_{bit}. In other words, the intra-pair length matching is much more stringent than the inter-pair length matching.

It is recommended that length matching of both signals of a differential pair be within 5 mils. Length matching should occur on a segment-by-segment basis. Segments might include the path between vias, resistor pads, capacitor pads, a pin, an edge-finger pad, or any combinations of them, etc. Length matching from one pair to any other should be within 100 mils.

Note that lengths should only be counted to the pins or pad edge. Additional etch within the edge-finger pad, for instance, is electrically considered part of the pad itself.

2.5.4 ESD Protection for HDMI Interface

In order to minimize the hazard of ESD, a set of protection diodes are highly recommended for each HDMI input (data and clock).

International standard EN 55024:1998 establishes 4kV as the common immunity requirement for contact discharges in electronic systems. 8kV is also established as the common immunity requirement for air discharges in electronic systems. International standard EN 61000-4-2:1995 / IEC 1000-4-2:1995 establishes the immunity testing and measurement techniques.

System level ESD testing to International standard EN 61000-4-2:1995 / IEC 1000-4-2:1995 has confirmed that the proper implementation of Chronitel recommended diode protection circuitry, using BCD AT1140 diode array devices, will protect the CH7101B device from HDMI transmitter discharges of greater than 19kV (contact) and 20kV (air). The AT1140 have a typical capacitance of only 0.50pF between I/O pins. This low capacitance won't bring too much bad effect on HDMI eye diagram test.

Figure7 (A) and (B) show the connection of HDMI connectors, including the recommended design of AT1140 diode array devices. HDMI connector is used to connect the CH7101B HDMI inputs from HDMI transmitter.

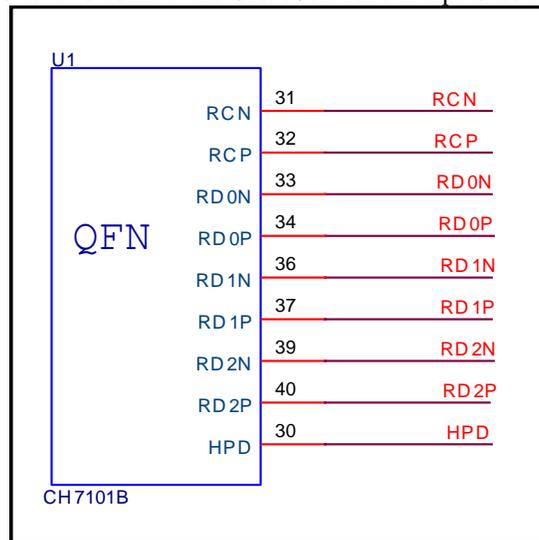


Figure 7(A): The connection of the HDMI input

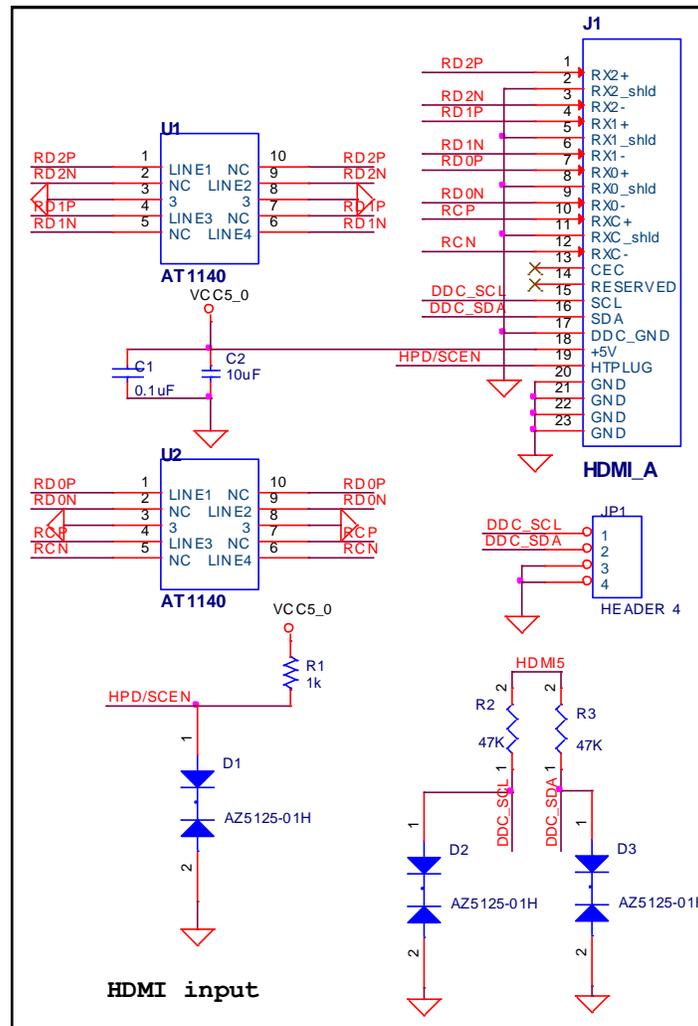


Figure 7(B): The connection of the HDMI inputs—CH7101B HDMI connectors

The following is the description for each HDMI interface pins

• **HDMI Link Data Channel (RD [2:0] P and RD [2:0] N)**

These pins provide HDMI differential inputs for data channel 0 (blue), data channel 1 (green) and data channel 2 (red). (Refer to **Figure 7 (A)**).

• **HDMI Link Clock Outputs (RCP and RCN)**

These pins provide the HDMI differential clock inputs for HDMI corresponding to data on the RD [2:0] P and RD [2:0] N inputs (Refer to **Figure 7 (A)**).

• **HPD (HDMI Hot Plug Detect)**

This output pin connects to the +5V power through a 1KΩ resistor. Refer to **Figure 7 (B)** for the design example.

2.6 Video Outputs

• **VGA or RGB+CSYNC output**

VGA standard output signal level of Hsync and Vsync is more than 2.4V. CH7101B Hsync and Vsync output signal level is +3.3V. Customer can use 74ACT08 (AND GATE) to pull high this signal level to 5V(recommend to add the diode). It is recommended but not necessary. (Refer to **Figure 8**)

In RGB+Csync output format, the Csync high level is +3.3V. Csync pin is a COMS push-pull output pin, customer can use other circuit to change is high level to 0.7V or other voltage level according to different Receivers. (Refer to **Figure 8**)

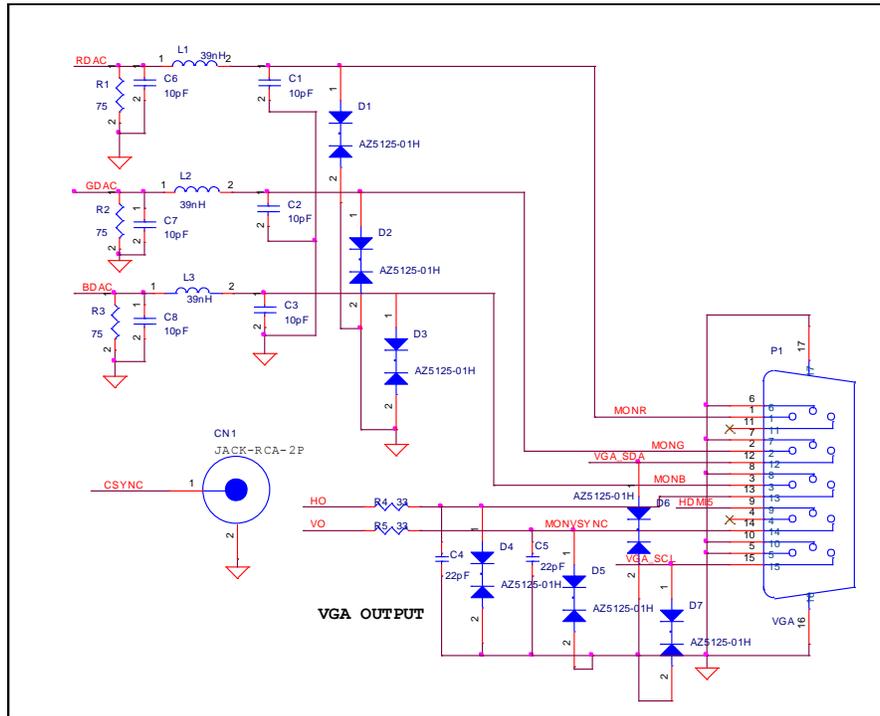


Figure 8: CH7101B VGA or RGB+CSYNC output

2.7 Audio Output

- IIS

IIS audio output can be configured through programming CH7101B registers. (Refer to **Figure 9**)

- SPDIF

For SPDIF output, CH7101B supports audio sample frequencies from 32Khz to 192kHz. (Refer to **Figure 9**)

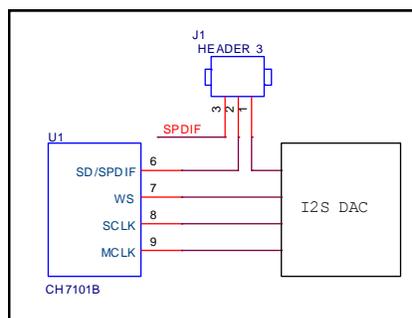
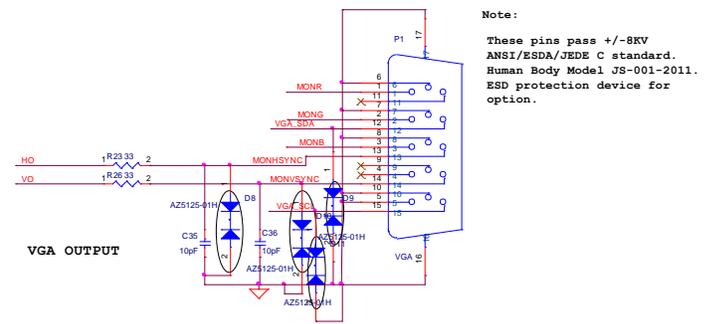
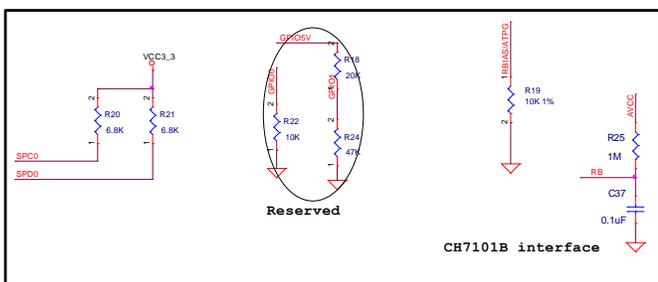
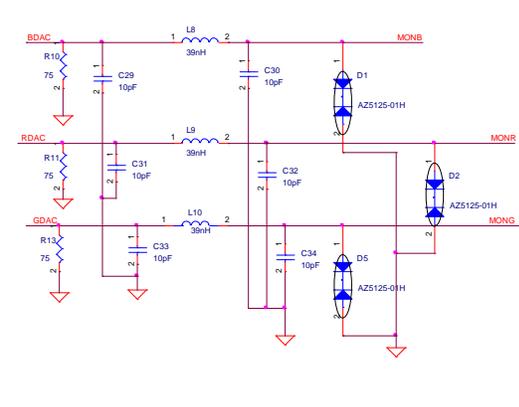
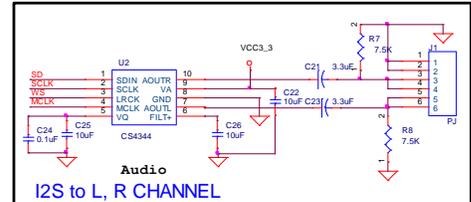
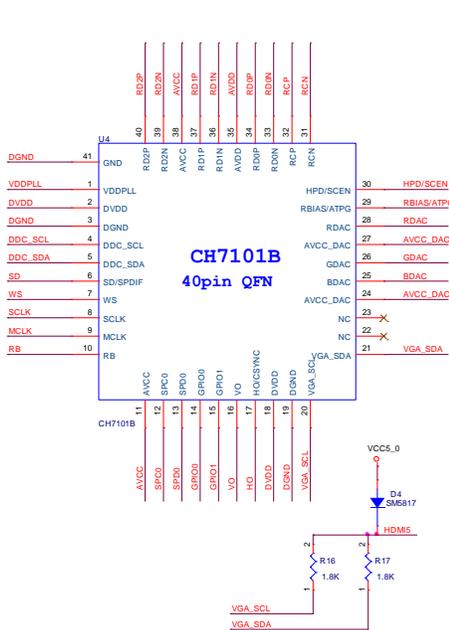
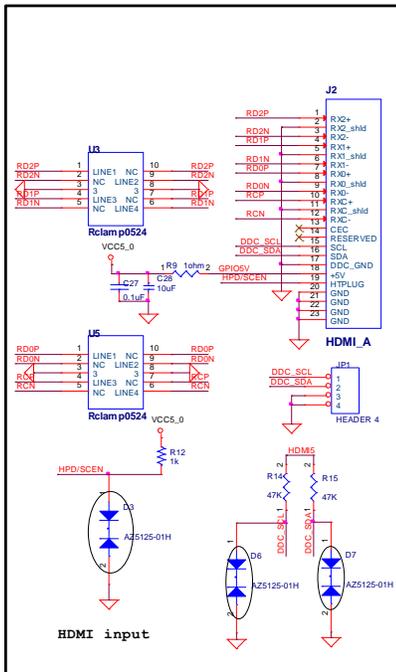
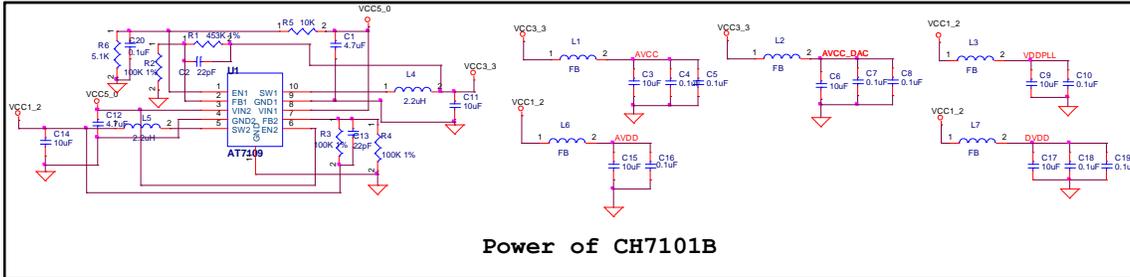


Figure 9: CH7101B IIS or SPDIF Output Pins

3.0 REFERENCE DESIGN EXAMPLE

The figures below are the reference schematic of CH7101B, which is provided here for design reference only. Please contact Chronitel Applications group for further support. **Table 3** provides the BOM list for the reference schematic.

3.1 Reference Schematic



Note:
These pins pass +/-8KV
ANSI/ESDA/JEDEC standard.
Human Body Model JS-001-2011.
ESD protection device for
option.

3.2 Reference Board Preliminary BOM

Table 3: CH7101B Reference Design BOM List

Item	Quantity	Reference	Part
1	2	C1, C12	4.7 μ F
2	2	C2, C13	22pF
3	11	C3, C6, C9, C11, C14, C15, C17, C22, C25, C26, C28	10 μ F
4	12	C4, C5, C7, C8, C10, C16, C18, C19, C20, C24, C27, C37	0.1 μ F
5	8	C29, C30, C31, C32, C33, C34, C35, C36	10pF
6	2	C21, C23	3.3 μ F
7	1	D4	SM5817
8	10	D1, D2, D3, D5, D6, D7, D8, D9, D10, D11	AZ5125-01H
9	1	JP1	Header 4
10	1	J2	HDMI_A
11	1	J1	PJ
12	8	L1, L2, L3, L6, L7	47 Ω _100MHz
13	3	L8, L9, L10	39nH
14	2	L4, L5	2.2 μ H
15	1	P1	VGA
16	1	R1	453K Ω 1%
17	3	R2, R3, R4	100K Ω 1%
18	3	R10, R11, R13	75 Ω
19	1	R12	1K Ω
20	3	R14, R15, R24	47K Ω
21	2	R5, R22	10K Ω
22	2	R20, R21	6.8K Ω
23	1	R19	10K Ω 1%
24	1	R18	20K Ω
25	2	R7, R8	7.5K Ω
26	1	R25	1M Ω
27	2	R23, R26	33 Ω
28	2	R16, R17	1.8K Ω
29	1	R9	1 Ω
30	1	R6	5.1K Ω
31	1	U1	AT7109
32	2	U2, U4	AT1140
33	1	U3	CH7101B
34	1	U5	CS4344

4.0 REVISION HISTORY

Rev. #	Date	Section	Description
0.1	10/17/2012	All	Initial release
0.2	11/30/2012	2.4 2.5.4 2.6 3.1 3.2	Modify VGA_SCL and SDA pull up resistor value Modify Figure5 (B) Modify Figure 6 Modify reference schematic Modify BOM
0.3	10/08/2014	All	Update for CH7101B
0.4	03/18/2016	2.3	Add RB
0.5	02/27/2018	2.3 3.1	Modify RB Modify reference schematic

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